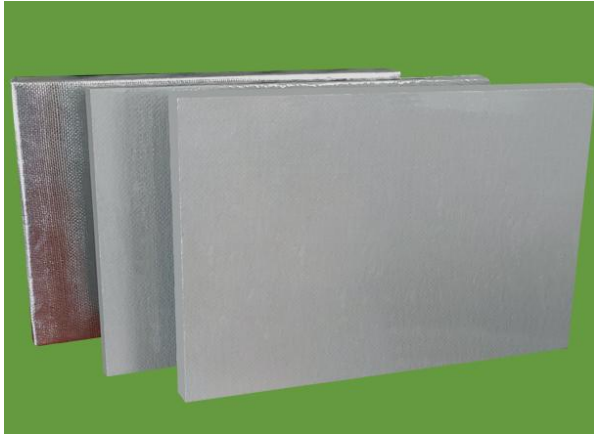


CCEWOOL® M60 Microporous Insulation Board



Temperature Grade: 600°C (1112°F)

CCEWOOL® M60 Microporous Insulation Board is an efficient insulation product based on advanced microporous insulation technology. At low temperature, it has a lower thermal conductivity than still air. The thermal conductivity increases very little with the increase of temperature. At high temperature, its insulation effect is 3-4 times higher than traditional insulation materials. CCEWOOL® M60 Microporous Insulation Board has high compressive strength, covered with aluminum foil or glass fiber cloth. It is an excellent

choice for the lightweight and energy-saving application of kiln.

Characteristics:

- Good fit to curved surfaces
- Low thermal conductivity
- Low heat storage
- Non-combustibility

Application:

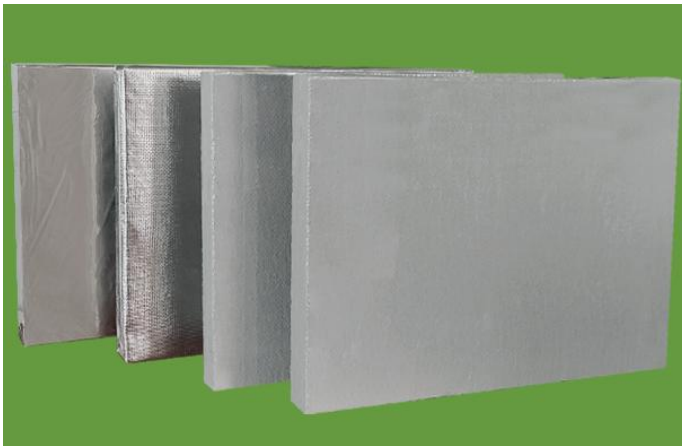
- Typical Applications
- Back-up insulation in high-temperature furnaces
- Appliances insulation
- Fire protection equipment
- Electronic devices
- Nonferrous Metal Furnace
- Rotary & Shaft Kiln
- Various Incinerator
- Reheating Furnace
- Permanent Lining For EAF Ladle
- General Industrial Furnace etc.

TDS

CCEWOOL® M60 Microporous Insulation Board	
Description	M60 Board
Recommended Temperature of Use (°C)	600 (1112°F)
Density (kg/m³)	300/320
Modules of Rupture (MPa)	≥0.15

Compressive Strength (MPa, 10% relative deformation)	≥0.3
Permanent Linear Shrinkage (%)	600°C x 24h ≤2.0
Thermal Conductivity (W/m·K)	
100°C	0.022
200°C	0.024
300°C	0.028
400°C	0.029
500°C	-
600°C	-
Covering Material	Aluminum Foil / PE Foil / Glass Fiber Cloth
Standard Size (mm)	600 x 400 x (10-50)
	1000 x 500 x (10-50)

CCEWOOL® M90 Microporous Insulation Board



Temperature Grade: 900°C (1652°F)

CCEWOOL® M90 Microporous Insulation Board is an efficient insulation product based on advanced microporous insulation technology. It has a lower thermal conductivity than stagnant air, making it an ideal high-temperature insulation material. The surface of the board can be coated with aluminum foil or PE shrink film. The nano board can also be coated with high-temperature glass fiber materials on the surface of nano-microporous insulation materials using a

special process, giving it low thermal conductivity while maintaining moderate flexibility, allowing for multidimensional bending to meet the requirements of special space applications.

Characteristics:

- Good fit to curved surfaces
- Excellent thermal shock resistance
- Excellent thermal stability
- Low thermal conductivity
- Low heat storage
- Non-combustibility



Application:

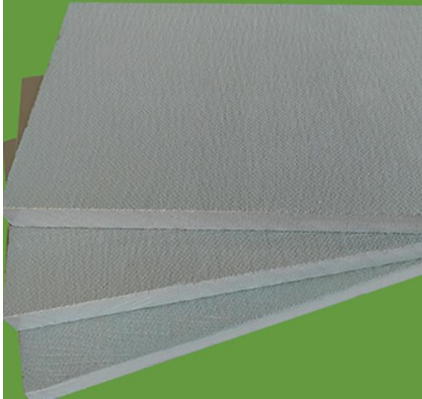
Typical Applications
 Back-up insulation in high-temperature furnaces
 Appliances insulation
 Fire protection equipment
 Electronic devices
 Nonferrous Metal Furnace
 Rotary & Shaft Kiln
 Various Incinerator
 Reheating Furnace
 Permanent Lining For EAF Ladle
 General Industrial Furnace etc.

TDS

CCEWOOL® M90 Microporous Insulation Board	
Description	M90 Board
Recommended Temperature of Use (°C)	900(1652°F)
Density (kg/m³)	280/300
Modules of Rupture (MPa)	≥0.15
Compressive Strength (MPa, 10% relative deformation)	≥0.3
Permanent Linear Shrinkage (%)	900°C x 24h ≤2.0
Thermal Conductivity (W/m·K)	
100°C	0.02
200°C	0.023
300°C	0.026
400°C	0.027
500°C	0.033
600°C	-
Covering Material	Aluminum Foil / PE Foil / Glass Fiber Cloth
	600 x 400 x (10-50)
Standard Size (mm)	1000 x 500 x (10-50)



CCEWOOL® M110 Microporous Insulation Board



Temperature Grade: 1100°C (2012°F)

CCEWOOL® M110 Microporous Insulation Board is a nanoscale microporous insulation material and is the best high-temperature solid insulation material with superior insulation performance to date. The surface can be covered with outer materials such as aluminum foil, glass fiber cloth, etc., to reduce dust, decrease damage, increase strength, and prevent moisture damage. At low temperatures, the product has a lower thermal conductivity than stagnant air, with a slight increase in thermal conductivity

as the temperature rises. It provides 3-4 times better insulation performance at high temperatures compared to traditional insulation materials.

CCEWOOL® M110 Microporous Insulation Board is an ideal material for reducing heat loss and improving energy efficiency, making it an excellent choice for applications such as kilns and other lightweight and energy-saving applications.



Characteristics:

Extremely low thermal conductivity, significantly reduces insulation layer thickness and improves insulation efficiency.

Low heat dissipation and heat storage, increases heating and cooling rates.

Environmentally friendly, non-toxic, and harmless.

Durable material, capable of self-support.

Excellent thermal stability.

Superior resistance to rapid temperature changes.

Application:

Back-up insulation in high-temperature furnaces

Appliances insulation

Fire protection equipment

Electronic devices

Nonferrous Metal Furnace

Rotary & Shaft Kiln

Various Incinerator

Reheating Furnace

Permanent Lining For EAF Ladle

General Industrial Furnace etc.



TDS

CCEWOOL® M110 Microporous Insulation Board	
Description	M110 Board
Recommended Temperature of Use (°C)	1100(2012°F)
Density (kg/m³)	320
Modules of Rupture (MPa)	≥0.15
Compressive Strength (MPa, 10% relative deformation)	≥0.3
Permanent Linear Shrinkage (%)	1050°C x 24h ≤2.5
Thermal Conductivity (W/m·K)	
100°C	0.022
200°C	0.024
300°C	0.031
400°C	0.036
500°C	0.04
600°C	0.048
Covering Material	Aluminum Foil / PE Foil / Glass Fiber Cloth
	600 x 400 x (10-50)
Standard Size (mm)	1000 x 500 x (10-50)

